General Purpose Transistor

NPN Silicon

Features

- Moisture Sensitivity Level: 1
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--------------------------------|------------------|---------------------------|------|
| Collector-Emitter Voltage | V _{CEO} | 40 | Vdc |
| Collector-Base Voltage | V _{CBO} | 75 | Vdc |
| Emitter-Base Voltage | V _{EBO} | 6.0 | Vdc |
| Collector Current - Continuous | Ic | 600 | mAdc |
| Electrostatic Discharge | ESD | HBM Class 2 MM Class B | |

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|--|-----------------------------------|-------------|------|
| Total Package Dissipation (Note 1), T _A = 25°C | P _D | 150 | mW |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 833 | °C/W |
| Junction and Storage Temperature | T _J , T _{stg} | -55 to +150 | °C |

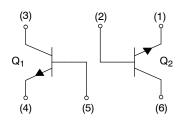
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

 Device mounted on FR4 glass epoxy printed circuit board using the minimum recommended footprint.



ON Semiconductor®

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SC-88/SC70-6/SOT-363 CASE 419B STYLE 1

MARKING DIAGRAM



1P = Specific Device Code

M = Date Code ■ Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|------------------|----------------------|-----------------------|
| MBT2222ADW1T1G | SOT-363 (Pb-Free) | 3000 / Tape & Reel |
| NSVBT2222ADW1T1G | SOT-363 (Pb-Free) | 3000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

| Ch | Symbol | Min | Max | Unit | | |
|---|---|----------------------|---|------------------------------|--------------------|--|
| OFF CHARACTERISTICS | | | | | | |
| Collector-Emitter Breakdown Voltage | $(I_C = 10 \text{ mAdc}, I_B = 0)$ | V _{(BR)CEO} | 40 | _ | Vdc | |
| Collector-Base Breakdown Voltage | $(I_C = 10 \mu Adc, I_E = 0)$ | V _{(BR)CBO} | 75 | - | Vdc | |
| Emitter-Base Breakdown Voltage, | $(I_E = 10 \mu Adc, I_C = 0)$ | V _{(BR)EBO} | 6.0 | - | Vdc | |
| Collector Cutoff Current | (V _{CE} = 60 Vdc, V _{EB(off)} = 3.0 Vdc) | I _{CEX} | - | 10 | nAdc | |
| Collector Cutoff Current | (V _{CB} = 60 Vdc, I _E = 0) (V _{CB} = 60 Vdc, I _E = 0, T _A = 125°C) | Ісво | - - | 0.01 10 | μAdc | |
| Emitter Cutoff Current | $(V_{EB} = 3.0 \text{ Vdc}, I_{C} = 0)$ | I _{EBO} | - | 100 | nAdc | |
| Base Cutoff Current | $(V_{CE} = 60 \text{ Vdc}, V_{EB(off)} = 3.0 \text{ Vdc})$ | I _{BL} | - | 20 | nAdc | |
| ON CHARACTERISTICS | | | • | • | • | |
| DC Current Gain | $ \begin{array}{c} (I_C=0.1 \text{ mAdc, } V_{CE}=10 \text{ Vdc}) \\ (I_C=1.0 \text{ mAdc, } V_{CE}=10 \text{ Vdc}) \\ (I_C=10 \text{ mAdc, } V_{CE}=10 \text{ Vdc}) \\ (I_C=10 \text{ mAdc, } V_{CE}=10 \text{ Vdc}) \\ (I_C=150 \text{ mAdc, } V_{CE}=10 \text{ Vdc, } T_A=-55^{\circ}\text{C}) \\ (I_C=150 \text{ mAdc, } V_{CE}=10 \text{ Vdc)} \text{ (Note 2)} \\ (I_C=150 \text{ mAdc, } V_{CE}=1.0 \text{ Vdc)} \text{ (Note 2)} \\ (I_C=500 \text{ mAdc, } V_{CE}=10 \text{ Vdc)} \text{ (Note 2)} \end{array} $ | h _{FE} | 35 50 75 35 100 50 40 | - - - 300 - - | - | |
| Collector-Emitter Saturation Voltage (N | lote 2) $ \begin{aligned} \text{(I}_{\text{C}} &= 150 \text{ mAdc, I}_{\text{B}} = 15 \text{ mAdc)} \\ \text{(I}_{\text{C}} &= 500 \text{ mAdc, I}_{\text{B}} = 50 \text{ mAdc)} \end{aligned} $ | V _{CE(sat)} | - - | 0.3 1.0 | Vdc | |
| Base - Emitter Saturation Voltage (Note | $V_{BE(sat)}$ | 0.6 - | 1.2 2.0 | Vdc | | |
| SMALL-SIGNAL CHARACTERISTICS | 3 | | | | | |
| Current-Gain - Bandwidth Product (No | te 3) (I _C = 20 mAdc, V _{CE} = 20 Vdc, f = 100 MHz) | f _T | 300 | _ | MHz | |
| Output Capacitance | (V _{CB} = 10 Vdc, I _E = 0, f = 1.0 MHz) | C _{obo} | - | 8.0 | pF | |
| Input Capacitance | $(V_{EB} = 0.5 \text{ Vdc}, I_{C} = 0, f = 1.0 \text{ MHz})$ | C _{ibo} | - | 25 | pF | |
| Input Impedance | (I _C = 1.0 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz) (I _C = 10 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz) | h _{ie} | 2.0 0.25 | 8.0 1.25 | kΩ | |
| Voltage Feedback Ratio | (I _C = 1.0 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz) (I _C = 10 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz) | h _{re} | - - | 8.0 4.0 | X 10 ⁻⁴ | |
| Small-Signal Current Gain | (I _C = 1.0 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz) (I _C = 10 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz) | h _{fe} | 50 75 | 300 375 | - | |
| Output Admittance | h _{oe} | 5.0 25 | 35 200 | μmhos | | |
| Collector Base Time Constant | rb, C _c | - | 150 | ps | | |
| Noise Figure (I _C = 100 | NF | - | 4.0 | dB | | |
| SWITCHING CHARACTERISTICS | | | | | | |
| Delay Time | (V _{CC} = 30 Vdc, V _{BE(off)} = -0.5 Vdc, | t _d | _ | 10 | | |
| Rise Time | I _C = 150 mAdc, I _{B1} = 15 mAdc) | t _r | - | 25 | ns | |
| Storage Time | (V _{CC} = 30 Vdc, I _C = 150 mAdc, | t _s | - | 225 | | |
| Fall Time | I _{B1} = I _{B2} = 15 mAdc) | | _ | 60 | ns | |

^{2.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%. 3. f_T is defined as the frequency at which $|h_{fe}|$ extrapolates to unity.

SWITCHING TIME EQUIVALENT TEST CIRCUITS

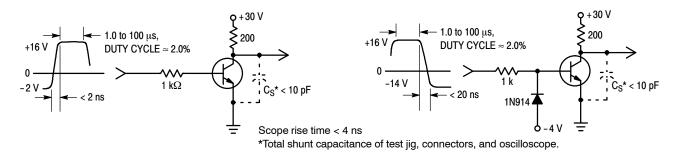


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

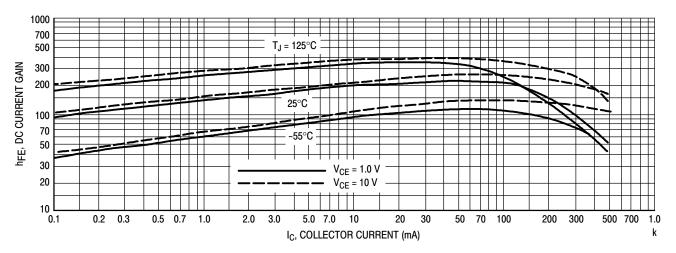


Figure 3. DC Current Gain

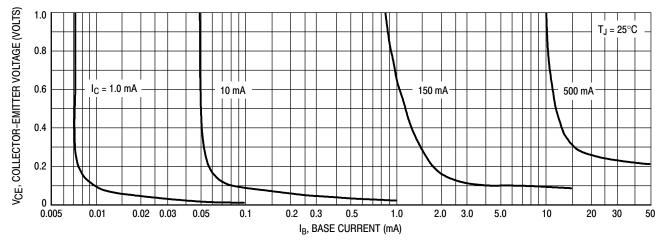


Figure 4. Collector Saturation Region

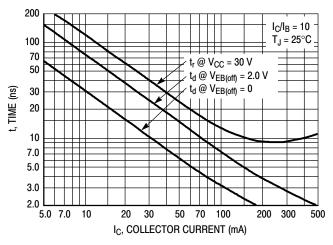


Figure 5. Turn-On Time

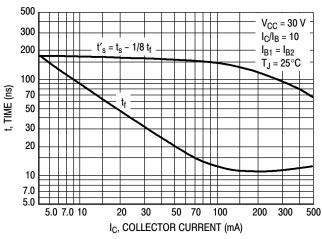


Figure 6. Turn - Off Time

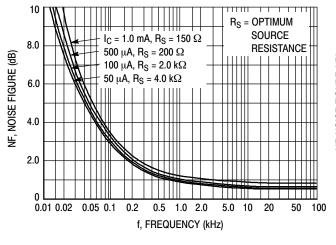


Figure 7. Frequency Effects

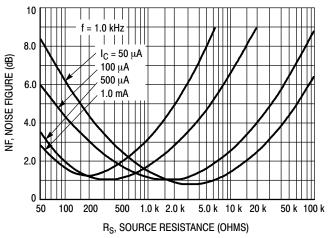


Figure 8. Source Resistance Effects

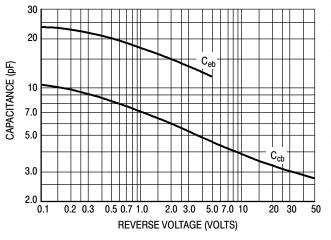


Figure 9. Capacitances

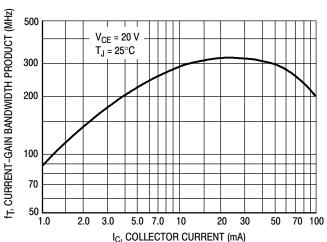
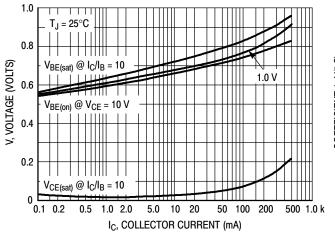


Figure 10. Current-Gain Bandwidth Product



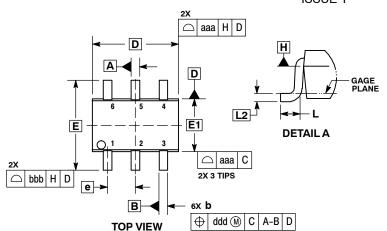
+0.5 R₀VC for V_{CE(sat)} COEFFICIENT (mV/°C) -0.5 -1.0 - 1.5 $R_{\theta VB}$ for V_{BE} -2.0 -2.5 100 200 0.1 0.2 0.5 1.0 2.0 5.0 10 500 I_C, COLLECTOR CURRENT (mA)

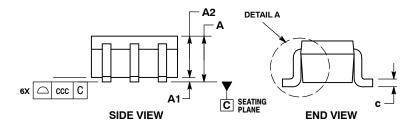
Figure 11. "On" Voltages

Figure 12. Temperature Coefficients

PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE Y**





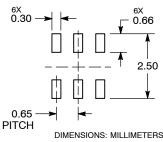
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,
- 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
 PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
- DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H.
- DATUMS A AND B ARE DETERMINED AT DATUM H.
 DIMENSIONS 6 AND c APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
 DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION.
- ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 5 AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER

| HADI | US OF T | HE FO |) I | I | | | |
|------|--------------------|----------|----------------|-----------|-----------|-------|--|
| | MILLIMETERS | | | INCHES | | | |
| DIM | MIN | NOM | MAX | MIN | NOM | MAX | |
| Α | | | 1.10 | | | 0.043 | |
| A1 | 0.00 | | 0.10 | 0.000 | | 0.004 | |
| A2 | 0.70 | 0.90 | 1.00 | 0.027 | 0.035 | 0.039 | |
| b | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 | |
| С | 0.08 | 0.15 | 0.22 | 0.003 | 0.006 | 0.009 | |
| D | 1.80 | 2.00 | 2.20 | 0.070 | 0.078 | 0.086 | |
| E | 2.00 | 2.10 | 2.20 | 0.078 | 0.082 | 0.086 | |
| E1 | 1.15 | 1.25 | 1.35 | 0.045 | 0.049 | 0.053 | |
| е | | 0.65 BSC | | | 0.026 BSC | | |
| L | 0.26 | 0.36 | 0.46 | 0.010 | 0.014 | 0.018 | |
| L2 | 0.15 BSC | | | 0.006 BSC | | | |
| aaa | 0.15 | | | 0.006 | | | |
| bbb | 0.30 | | | 0.012 | | | |
| ccc | 0.10 | | | 0.004 | | | |
| ddd | | 0.10 | 0.10 0.004 | | | | |

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1

EMITTER 1 BASE 1 COLLECTOR 2

RECOMMENDED SOLDERING FOOTPRINT*



details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

*For additional information on our Pb-Free strategy and soldering

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